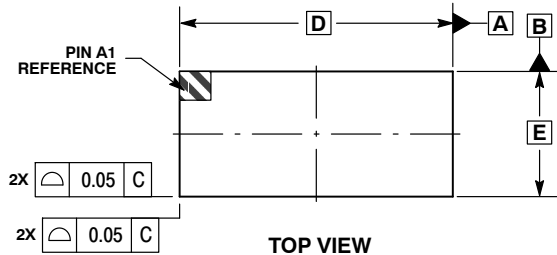




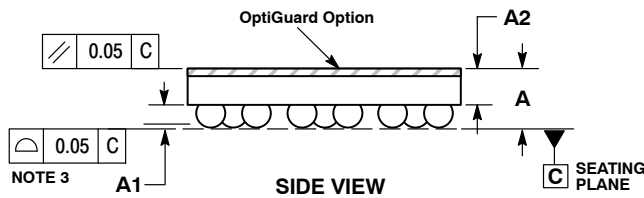
SCALE 4:1

WLCSP15, 3.01x1.38
CASE 567BT
ISSUE O

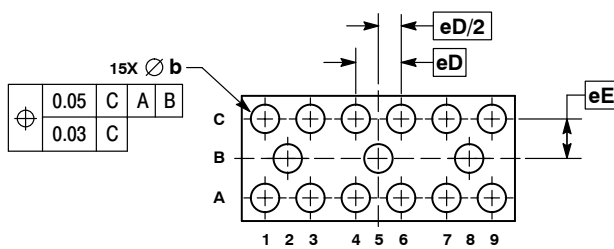
DATE 26 JUL 2010



TOP VIEW



SIDE VIEW

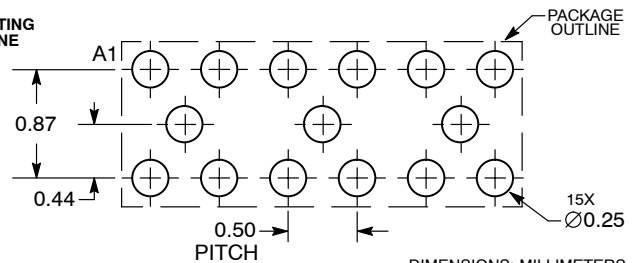


BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42	REF
b	0.29	0.35
D	3.01	BSC
E	1.38	BSC
eD	0.50	BSC
eE	0.435	BSC

**RECOMMENDED
SOLDERING FOOTPRINT***


DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION: WLCSP15, 3.01X1.38

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